

4th December 2018							
Venue	Virgo 1		Virgo 2		Virgo 3		
07:30-08:30hrs	Registration @ Leo 1's Foyer						
08:30-12:00hrs (210 min)	PDC 1 : Introduction to Fan-out Wafer Level Packaging Dr. Beth Keser Director, Packaging Engineering, Intel Corporation		PDC 2: Advanced Integrated Circuit Design for Reliability Dr. Richard Rao Fellow, Microsemi Corp		PDC 3: 3D SIP For ASIC and DRAM Integration Dr. Li Li Distinguished Engineer, Cisco Systems Inc		
12:00-13:30hrs	Lunch						
13:30-17:00hrs (210 min)	PDC 4 : Understanding Flip Chip Technology and Its Applications Mr. Eric Perfecto Principal Member of the Technical Staff, GLOBALFOUNDRIES		PDC 5: Introduction to 3D Interconnect and Packaging Technologies Prof. Sarah Kim Seoul National University of Science and Technology		PDC 6: Power Electronic Packaging Reliability, Materials, Assembly and Simulation Dr. Ning-Cheng Lee, Vice President of Technology, Indium Corporation Dr. Yong Liu, Principal Member of Tech Staff, ON Semi Prof. Sheng Liu, Dean of the School of Power and Mechanical Engineering and the Institute of Technological Science of Wuhan University		
5th December 2018							
LEO 1- 4							
08:00-08:45hrs	Registration @ Leo 1's Foyer						
08:45-09:30hrs (45 min)	Opening Ceremony						
09:30-10:15hrs (45 min)	Keynote 1: Mr. Ivor Barber, Vice President, Packaging Engineering, AMD.						
10:15-10:45hrs (30 min)	Coffee/Tea Break						
10:45-11:30hrs (45 min)	Keynote 2: Dr. Avram Bar-Cohen, Principal Engineering Fellow, Raytheon Corporation and President, EPS.						
11:30-12:15hrs (45 min)	Keynote 3: Ms Jean Trehwella , Director, Packaging Research and Development, GLOBALFOUNDRIES.						
12:15-13:30hrs (75 min)	EPS Luncheon						
13:30-15:30hrs (120 min)	Plenary Session 1: Heterogeneous Packaging Dr. William Chen, ASE Fellow and Senior Technical Advisor, ASE (Moderator) 1. Dr. Gamal Refai-Ahmed, Life Fellow ASME, Fellow CAE, Distinguished Engineer, Xilinx 2. Mr. Mike Delaus, Manager, Analog Devices 3. Mr. Manish Ranjan, Director, Lam Research 4. Dr. Yu-Po Wang, Senior Director CRD Center, SPIL						
15:30-16:00hrs (30 min)	Coffee/Tea Break						
16:00-18:00hrs (120 min)	Plenary Session 2: Packaging for next generation automobiles/autonomous vehicles Dr. Seung Wook YOON, Director, STATS ChipPAC ( Moderator) 1. Dr. Gaurab Majumdar, Senior Fellow, Mitsubishi Electric Corporation 2. Ms. LC Tan, Sr. Director, NXP Semiconductors 3. Mr. Christophe Bouquet, Director, Infineon Technologies 4. Mr. Santosh Kumar , Director, Yole Development						
18:30-20:30hrs	VIP Dinner						
6th December 2018							
Venue	Gemini 2	Leo 1	Leo 2	Leo 3	Leo 4	Gemini 1	
08:30-09:00hrs (30 min)	Invited #1 : Mr. Sam Karikalan	Invited #2 : Prof. Tan Chuan Seng	Invited #3 : Ms. Lim Sze Pei	Invited #4 : Dr. Gokul Kumar	Invited #5 : Dr. Robert Kao		
09:00-10:00hrs A01-A15	Advanced Packaging I	Interconnect Technologies I	Materials and Processing I	Emerging Technologies I	Thermal Characterization & Cooling Solutions I		
10:00-11:00hrs (60 Min)	Coffee/Tea break & Interactive Session I Exhibitor Presentation 1						
11:00-12:20hrs B01-B20	Advanced Packaging II	Quality, Reliability & Failure Analysis I	Materials and Processing II	Electrical Simulation & Characterization I	Mechanical Simulation & Characterization I		
12:20-13:50hrs (90 min)	Lunch ; Best paper Awards, EPTC 2018 committee Appreciation						
13:50-14:20hrs (30 min)	Invited #6 : Dr. Han-Ping Pu	Invited #7 : Dr. Kedar Hardikar	Invited #8: Dr. Dongshun Bai	Invited #9: Dr. Tanja Braun	Invited #10 : Dr. Stevan Hunter		
14:20-15:40hrs C01-C20	TSV & WLB Packaging I	Quality, Reliability & Failure Analysis II	Materials and Processing III	Emerging Technologies II	Electrical Simulation & Characterization II	Heterogeneous Integration Roadmap Workshop (Parallel Session to Technical paper tracks)	
15:40-16:40hrs (60 min)	Coffee/Tea break & Interactive Session 1 Exhibitor Presentation 2						
16:40-18:00hrs D01-D20	Thermal Characterization & Cooling Solutions II	Interconnect Technologies II	Materials and Processing IV	Emerging Technologies III	Mechanical Simulation & Characterization II		
18:30-21:30hrs (180 min)	Conference Banquet						
7th December 2018							
Venue	Gemini 2	Leo 1	Leo 2	Leo 3	Leo 4		
08:30-09:00hrs (30 min)	Invited #11 : Dr. Soon-Wook Kim	Invited #12 : Prof. David Harvey	Invited #13: Mr. Shunsuke Tonouchi	Invited #14 : Ms. Rozalia Beica	Invited #15 Prof. Andrew Tay		
09:00-10:20hrs E01-E20	TSV & WLB Packaging II	Interconnect Technologies III	Materials and Processing V	Emerging Technologies IV	Thermal Characterization & Cooling Solutions III		
10:20-11:10hrs (50 min)	Coffee/Tea break & Interactive Session 2 Exhibitor Presentation 3						
11:10-12:30hrs F01-F20	Advanced Packaging III	Equipment and Process Automation	Materials and Processing VI	Electrical Simulation & Characterization III	Mechanical Simulation & Characterization III		
12:30-13:30 hrs (60 min)	Lunch ; EPTC 2019 Introduction; Sponsors appreciation;						
13:30-14:00hrs (30 min)	Invited #16: Mr. Minwoo Daniel Rhee	Invited #17 Mr. Kei Murayama	Invited #18: Prof. Jeff Suhling	Invited #19 : Dr. Bill Bottoms	Invited #20 Prof. Marta Rencz		
14:00-15:20hrs G01-G20	TSV & WLB Packaging III	Interconnect Technologies IV	Quality, Reliability & Failure Analysis III	Emerging Technologies V	Thermal simulation and modeling IV		
15:20-15:40hrs (20 min)	Coffee/Tea break & Interactive Session 2						
Virgo 1- 4							
15:40-17:40hrs (120 min)	Plenary session 3 : Next Generation Packaging Technologies Mr. Shigenori Aoki, Fujitsu Laboratories ( Moderator) 1. Dr. Yasumitsu Orii, NAGASE "Packaging Technologies for Brain-inspired Devices in the era of AI/OT" 2. Mr. Yasushi Masuda, Fujitsu Advanced Technologies "Challenges and opportunities of packaging technologies for next generation computer systems" 3. Dr. Hideyuki Nasu, Furukawa Electric "VCSEL-based Optical Interconnects" 4. Dr. Toshihisa Nonaka, Hitachi Chemical "Material technology can drive advanced packaging"						
17:40-18:00hrs (20 min)	Closing Ceremony and Lucky Draw						